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**TRANSMITTAL LETTER TO THE UNITED STATES
DESIGNATED/ELECTED OFFICE (DO/EO/US)**

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INTERNATIONAL FILING DATE
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12 OCTOBER 1999 (12.10.99)

TITLE OF INVENTION

RESIN STRUCTURE AND USE THEREOF

APPLICANT(S) FOR DO/EO/US

Hideo Matsuoka, Mitsushige Hamaguchi, and Kazuhiko Kobayashi

Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items under 35 U.S.C. 371:

1. ☒ This express request to immediately begin national examination procedures (35 U.S.C. 371(f)).
2. ☒ The U.S. National Fee (35 U.S.C. 371(c)(1)) and other fees as follows:

CLAIMS	(1) FOR	(2) NUMBER FILED	(3) NUMBER EXTRA	(4) RATE	(5) CALCULATIONS
TOTAL CLAIMS	20	-20=	0	x \$18.00	
INDEPENDENT CLAIMS	3	-3=	0	x \$84.00	
MULTIPLE DEPENDENT CLAIM(S) (if applicable)				+ \$280.00	\$280.00
BASIC NATIONAL FEE (37 CFR 1.492(a)(1)-(4)):					
<input type="checkbox"/> International preliminary examination fee paid to USPTO (37 CFR 1.482).....\$710.00					
<input type="checkbox"/> No international preliminary examination fee paid to USPTO (37 CFR 1.482) but international search fee paid to USPTO (37 CFR 1.445(a)(2)).....\$740.00					
<input type="checkbox"/> Neither international preliminary examination fee (37 CFR 1.482) nor international search fee (37 CFR 1.445(a)(2)) paid to USPTO.....\$1,040.00					
<input type="checkbox"/> International preliminary examination fee paid to USPTO (37 CFR 1.482) and all claims satisfied provisions of PCT Article 33(2) to (4).....\$ 100.00					
<input checked="" type="checkbox"/> International Search Report enclosed\$890.00					\$890.00
Surcharge of \$_____ for furnishing the National fee or oath or declaration later than <input type="checkbox"/> 20 <input type="checkbox"/> 30 mos. from the earliest claimed priority date (37 CFR 1.482(e)).					\$130.00
TOTAL OF ABOVE CALCULATIONS					\$1,170.00
Reduction by ½ for filing by small entity, if applicable. Affidavits must be filed also. (Note 37 CFR 1.9, 1.27, 1.28.)					
SUBTOTAL					\$1,170.00
Processing fee of \$_____ for furnishing the English Translation later than <input type="checkbox"/> 20 <input type="checkbox"/> 30 mos. from the earliest claimed priority date (37 CFR 1.482(f)).					\$130.00
TOTAL NATIONAL FEE					\$1,170.00
Fee for recording the enclosed assignment (37 CFR 1.21(h)).					\$40.00
TOTAL FEES ENCLOSED					\$1,210.00

- a. ☒ A check in the amount of \$1,210.00 to cover the above fees is enclosed.
- b. ☐ Please charge my Deposit Account No. 13-3405 in the amount of \$_____ to cover the above fees.
A duplicate copy of this sheet is enclosed.
- c. ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 13-3405. A duplicate copy of this sheet is enclosed.

JOSEPH W. HARRIS 04 APR 2002

3. A copy of the International Application as filed (35 U.S.C. 371(c)(2))
- a. ☐ is transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US).
 - c. ☒ has been transmitted by the International Bureau.
4. ☒ A translation of the International Application into English (35 U.S.C. 371(c)(2)).
5. Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3))
- a. ☐ are transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ have been transmitted by the International Bureau.
6. ☐ A translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371(c)(3)).
7. ☒ An oath or declaration of the inventor (35 U.S.C. 371(c)(4)).
8. ☐ A translation of the Annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).

Other document(s) or information included:

9. ☒ An Information Disclosure Statement under 37 C.F.R. 1.97 and 1.98.
10. ☒ An Assignment document for recording and a Recordation Form Cover Sheet - Patents Only. Please mail the recorded assignment document to the person whose signature, name and address appears at the bottom of this page.
11. The above checked items are being transmitted
- a. ☐ before the 18th month publication.
 - b. ☐ after publication and the Article 20 communication but before 20 months from the priority date.
 - c. ☐ after 20 months but before 22 months (surcharge and/or processing fee included).
 - d. ☐ after 22 months (surcharge and/or processing fee included).
- Note:** Petition to revive (37 C.F.R. 1.137(a) or (b)) is necessary if 35 U.S.C. 371 requirements submitted after 22 months *and no proper demand for International Preliminary Examination was made by 19 months from the earliest claimed priority date.*
- e. ☒ by 30 months and a proper demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date.
 - f. ☐ after 30 months but before 32 months and a proper demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date (surcharge and/or processing fee included).
 - g. ☐ after 32 months (surcharge and/or processing fee included).
- Note:** Petition to revive (37 C.F.R. 1.137(a) or (b)) is necessary if 35 U.S.C. 371 requirements submitted after 32 months and a proper demand for International Preliminary Examination was made by 19 months from the earliest claimed priority date.
12. At the time of transmittal, the time limit for amending claims under Article 19
- a. ☐ has expired and no amendments were made.
 - b. ☐ has not yet expired.
13. ☐ Certain requirements under 35 U.S.C. 371 were previously submitted by the applicant on _____, namely:

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Date: 4 APR 2002

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- 2文字コード及び他の略語については、定期発行される各PCTガゼットの巻頭に掲載されている「コードと略語のガイダンスノート」を参照。

(54) Title: RESIN STRUCTURE AND USE THEREOF

(54) 発明の名称: 樹脂構造体およびその用途

(57) Abstract: A thermoplastic resin structure characterized in that it comprises a resin composition consisting substantially of 5 to 80 vol.% polyamide resin (a) and 95 to 20 vol.% polyphenylene sulfide resin (b) and, when examined with an electron microscope, shows separated resin phases in which the polyphenylene sulfide resin (b) constitutes a matrix phase (continuous phase) and the polyamide resin (a) constitutes a dispersed phase. This structure gives plastic containers, tubular objects, and accessories of these which each is excellent in barrier properties, strength, durability, and moldability.

(57) 要約:

実質的に (a) ポリアミド樹脂 5～80 容量%および (b) ポリフェニレンスルフィド樹脂 95～20 容量%からなる樹脂組成物で構成され、かつ、電子顕微鏡で観察される樹脂相分離構造において (b) ポリフェニレンスルフィド樹脂がマトリクス相 (連続相)、(a) ポリアミド樹脂が分散相となる相構造を形成することを特徴とする熱可塑性樹脂構造体であり、この構造体はバリア性、強度、耐久性、成形加工性に優れたプラスチック容器、管状体およびその付属部品を与える。

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4/PRY

DESCRIPTION

RESIN STRUCTURES AND THEIR USE

TECHNICAL FIELD

The present invention relates to thermoplastic resin structures of good vapor and/or liquid transmission resistance, and their use. In particular, the invention relates to resin moldings of specific transmission resistance, low water absorption, dimensional stability in wet and workability, which are obtained by forming a specific morphology of polyamide resin and polyphenylene sulfide resin and are favorable for vapor and/or liquid barrier articles, to multi-layer structures favorable for containers and pipes for storage and transportation of liquid chemicals such as oil and gasoline, to those favorable for wrapping and packaging materials and containers for foods and medicines, and to their use.

BACKGROUND ART

Having good mechanical properties, heat resistance, chemical resistance and moldability in good balance, polyamide resins are widely used, for example, for parts of electric and electronic appliances and for automobile parts. The recent requirement increasing in the art is for gas-barrier (transmission-resistant) resin articles capable of preventing

the contents from leaking out and protecting them from the open air for ensuring the safety and the storage stability of the contents and for protecting the environment from pollution. For those, polyamide resins are especially preferred and are used for various moldings, as their gas barrier properties are good. When wetted, polyamide resins become tougher, but, on the contrary, their dimensional stability and stiffness lowers. Especially when used in high humidity, their transmission resistance against liquid chemicals and gases lowers. Therefore, their use is often limited, and it is desired to improve them.

For improving for the physical properties of such polyamide resins, resin compositions and moldings consisting of a combination of polyamide resin and polyphenylene sulfide resin (hereinafter referred to as PPS resin) have heretofore been proposed, in which the PPS resin has good waterproofness and good transmission resistance but its toughness and moldability is not so good.

The method could improve the dimensional stability and the stiffness of the resin compositions and moldings in wet over that of moldings of polyamide resin alone, but is still unsatisfactory. When the resin compositions and moldings are used for structures that are required to have good transmission resistance and toughness, they are not satisfactory. Therefore desired are molding materials that comprise polyamide resin

and PPS resin and have both the good properties of polyamide resin and the good properties of PPS resin in good balance.

In multi-layer structures having a barrier layer of good barrier resin, one typical example of the resin to form the barrier layer is polyamide resin (for example, as in JP-A 220738/1983). However, the recent tendency in the field of automobile fuel is being toward using a mixture of gasoline and alcohol, gasohol, for which the plastic containers obtainable in the above-mentioned prior art are unsatisfactory in point of their barrier properties. Therefore desired is a technique of further improving the barrier properties of plastic containers.

On the other hand, it is known that PPS resin has extremely good barrier properties against liquid chemicals such as gasoline and automobile oil, and against water and carbon dioxide. Blow-molded containers and tubular structures of such PPS resin have been proposed (for example, as in JP-A 90216/1987, 255832/1986, 32816/1991). However, since its interlayer adhesiveness to other resin is poor, PPS resin has some problems in that its coextrusion and lamination with other resin materials such as polyethylene, polypropylene and other polyolefins is difficult.

The present invention is to realize a high-level balance of the mechanical strength and the toughness of polyamide resin and the low water absorption and the transmission resistance

of PPS resin, and its object is to provide thermoplastic resin structures which are so improved to the highest possible degree that they are free from the reduction in the mechanical properties such as dimensional stability and stiffness and the reduction in the liquid chemical and vapor transmission resistance intrinsic to polyamide resin in wet, especially to provide polyamide-PPS resin moldings favorable for vapor and/or liquid barrier articles, and to provide multi-layer structures of good transmission resistance, moldability, workability, interlayer adhesiveness and toughness that are favorable to plastic containers and can be stably and economically formed into good plastic containers.

DISCLOSURE OF THE INVENTION

We, the present inventors have studied to solve the problems noted above, and, as a result, have found that, when a polyamide resin and a PPS resin are mixed in a specific ratio optionally along with an inorganic filler in such a controlled manner that the PPS resin phase in morphology in the resulting resin composition could form a dispersed configuration capable of being a continuous phase in the shaped structure of the resin composition, then the above-mentioned problems can be solved. On the basis of this finding, we have reached the present invention.

Specifically, the invention provides the following:

(1) A thermoplastic resin structure formed of a resin composition that comprises substantially (a) from 5 to 80 % by volume of a polyamide resin and (b) from 20 to 95 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, the polyphenylene sulfide resin (b) forms a matrix phase (continuous phase) and the polyamide resin (a) forms a disperse phase;

(2) The thermoplastic resin structure of above (1), for which the blend ratio of the polyamide resin (a) and the polyphenylene sulfide resin (b) is such that the former accounts for from 55 to 80 % by volume and the latter for from 20 to 45 % by volume;

(3) The thermoplastic resin structure of above (1), for which the blend ratio of the polyamide resin (a) and the polyphenylene sulfide resin (b) is such that the former accounts for from 60 to 75 % by volume and the latter for from 25 to 40 % by volume;

(4) A thermoplastic resin structure formed of a resin composition that comprises (a) from 15 to 85 % by volume of a polyamide resin and (b) from 15 to 85 % by volume of a polyphenylene sulfide resin and contains (c) from 0 to 200 parts by weight of an inorganic filler relative to 100 parts by weight of the resin mixture of (a) and (b), which is characterized in that, in morphology therein seen through electronic

microscopy, both the phase of the polyphenylene sulfide resin (b) and the phase of the polyamide resin (a) are substantially continuous phases;

(5) A thermoplastic resin structure formed of a resin composition that comprises (a) from 55 to 95 % by volume of a polyamide resin and (b) from 5 to 45 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, the polyamide resin (a) forms a continuous phase and the polyphenylene sulfide resin (b) forms a laminar disperse phase;

(6) The thermoplastic resin structure of any of claims 1 to 5, which contains (c) from 0.5 to 200 parts by weight of an inorganic filler relative to 100 parts by weight of the total of the polyamide resin (a) and the polyphenylene sulfide resin (b);

(7) Moldings of the thermoplastic resin structure of any of above (1) to (6), which are formed in at least one method of injection molding, injection compression molding or compression molding;

(8) Containers for transportation or storage of liquid chemicals or gases, which are obtained by working the thermoplastic resin structure of any of above (1) to (7);

(9) Attached parts for containers for transportation or storage of liquid chemicals or gases, which are obtained by working the thermoplastic resin structure of any of above (1)

to (7);

(10) A multi-layer structure with a barrier layer, in which the barrier layer is formed of the thermoplastic resin structure of any of above (1) to (6);

(11) The multi-layer structure of above (10), wherein a neighboring layer is formed on one or both surfaces of the barrier layer, and the neighboring layer is a thermoplastic resin layer differing from the thermoplastic resin structure that forms the barrier layer;

(12) The multi-layer structure of above (11), wherein the thermoplastic resin to form the neighboring layer is at least one selected from polyolefin resins, thermoplastic polyester resins, polyamide resins, polycarbonate resins and ABS resins;

(13) The multi-layer structure of above (11), wherein the thermoplastic resin to form the neighboring layer is high-density polyethylene;

(14) The multi-layer structure of above (11), which has an adhesive layer formed between the barrier layer and the neighboring layer;

(15) The multi-layer structure of any of above (10) to (14), which is formed through coextrusion;

(16) The multi-layer structure of any of above (10) to (15), which is formed into multi-layered tubes or multi-layered blow moldings through coextrusion.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 shows a model of the morphology of a resin structure in which the continuous phase is formed of a PPS resin component (PPS) and the disperse phase is formed of a polyamide resin component (PA).

Fig. 2 shows a model of the morphology of a resin structure in which a PPS resin component and a polyamide resin component both form substantially continuous phases.

Fig. 3 shows a model of the morphology of a resin structure in which the continuous phase is formed of a polyamide resin component and the disperse phase is formed of a large number of thin, two-dimensional laminae (layers) of a PPS resin component.

Fig. 4 is an electronmicroscopic picture showing the separated morphology of the resin structure obtained in Example 13, in which the dark part is formed of a PPS resin component.

Fig. 5 is an electronmicroscopic picture showing the separated morphology of the resin structure obtained in Example 14, in which the dark part is formed of a PPS resin component.

Fig. 6 is an electronmicroscopic picture showing the separated morphology of the resin structure obtained in Example 15, in which the dark part is formed of a PPS resin component.

Fig. 7 is an electronmicroscopic picture showing the separated morphology of the resin structure obtained in

Comparative Example 5, in which the dark part is formed of a PPS resin component.

BEST MODES OF CARRYING OUT THE INVENTION

Embodiments of the invention are described below.

"Weight" referred to herein means "mass".

The polyamide resin (a) for use in the invention comprises, as the essential constituent components, amino acid, lactam or diamine, and dicarboxylic acid. Typical examples of the essential constituent components are amino acids such as 6-aminocaproic acid, 11-aminoundecanoic acid, 12-aminododecanoic acid, para-aminomethylbenzoic acid; lactams such as ϵ -caprolactam, ω -laurolactam; aliphatic, alicyclic or aromatic diamines such as tetramethylenediamine, hexamethylenediamine, 2-methylpentamethylenediamine, nonamethylenediamine, undecamethylenediamine, dodecamethylenediamine, 2,2,4-/2,4,4-trimethylhexamethylenediamine, 5-methylnonamethylenediamine, metaxylylenediamine, paraxylylenediamine, 1,3-bis(aminomethyl)cyclohexane, 1,4-bis(aminomethyl)cyclohexane, 1-amino-3-aminomethyl-3,5,5-trimethylcyclohexane, bis(4-aminocyclohexyl)methane, bis(3-methyl-4-aminocyclohexyl)methane, 2,2-bis(4-aminocyclohexyl)propane,

bis(aminopropyl)piperazine, aminoethylpiperazine; and aliphatic, alicyclic or aromatic dicarboxylic acids such as adipic acid, suberic acid, azelaic acid, sebacic acid, dodecanedicarboxylic acid, terephthalic acid, isophthalic acid, 2-chloroterephthalic acid, 2-methylterephthalic acid, 5-methylisophthalic acid, 5-sodium-sulfoisophthalic acid, 2,6-naphthalenedicarboxylic acid, hexahydroterephthalic acid, hexahydroisophthalic acid. In the invention, nylon homopolymers or copolymers derived from these starting compounds may be used either singly or as combined.

Especially useful in the invention are heat-resistant and strong polyamide resins having a melting point of not lower than 150°C. Concretely, they include polycapramide (nylon 6), polyhexamethylenadipamide (nylon 66), polytetramethylenadipamide (nylon 46), polyhexamethylenesebacamide (nylon 610), polyhexamethylenedodecamide (nylon 612), polyundecanamide (nylon 11), polydodecanamide (nylon 12), polycaproamide/polyhexamethylenadipamide copolymer (nylon 6/66), polycapramide/polyhexamethyleneterephthalamide copolymer (nylon 6/6T), polyhexamethylenadipamide/polyhexamethyleneterephthalamide copolymer (nylon 66/6T), polyhexamethylenadipamide/polyhexamethylenisophthalamide copolymer (nylon 66/6I),

polyhexamethyleneterephthalamide/polyhexamethylenisophthalamide copolymer (nylon 6T/6I), polyhexamethyleneterephthalamide/polydodecanamide copolymer (nylon 6T/12), polyhexamethylenadipamide/polyhexamethyleneterephthalamide/polyhexamethylenisophthalamide copolymer (nylon 66/6T/6I), polyxylylenadipamide (nylon XD6), polyhexamethyleneterephthalamide/poly-2-methylpentamethyleneterephthalamide copolymer (nylon 6T/M5T), polynonamethyleneterephthalamide (nylon 9T), and their mixtures and copolymers.

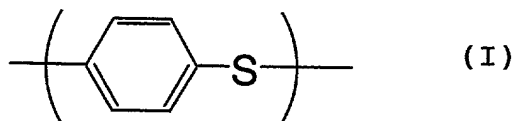
Especially preferred are copolymers having hexamethyleneterephthalamide units, such as nylon 6, nylon 66, nylon 610, nylon 6/66 copolymer, nylon 6T/66 copolymer, nylon 6T/6I copolymer, nylon 6T/12 and nylon 6T/6 copolymer. Also preferred in practical use are mixtures of these polyamide resins combined in accordance with the necessary properties such as impact resistance, moldability and miscibility.

The degree of polymerization of the polyamide resins is not specifically defined. For example, preferred are those having a relative viscosity of from 1.5 to 7.0, more preferably from 2.0 to 6.0, measured in a 98 % concentrated sulfuric acid solution having a sample concentration of 0.01 g/ml at 25°C.

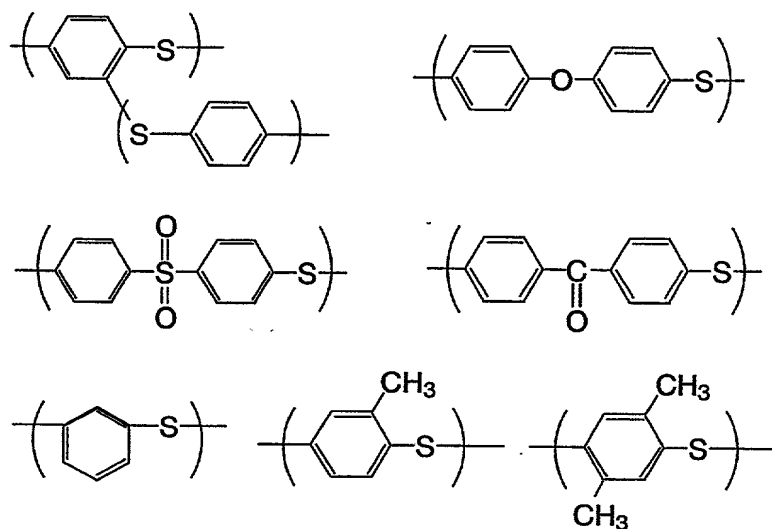
Preferably, the polyamide resin for use in the invention contains a copper compound for improving the long-term heat

resistance thereof. Examples of the copper compound are cuprous chloride, cupric chloride, cuprous bromide, cupric bromide, cuprous iodide, cupric iodide, cupric sulfate, cupric nitrate, copper phosphate, cuprous acetate, cupric acetate, cupric salicylate, cupric stearate, cupric benzoate, and chelate compounds of such an inorganic copper halide with xylylenediamine, 2-mercaptobenzimidazole or benzimidazole. Especially preferred are cuprous compounds, and more preferred are cuprous halides. Examples of the preferred copper compounds are cuprous acetate and cuprous iodide. The amount of the copper compound to be added to the polyamide resin preferably falls between 0.01 and 2 parts by weight, more preferably between 0.015 and 1 part by weight, relative to 100 parts by weight of the polyamide resin. If too much, the copper compound will release metal copper while the resin composition is molded in melt, and will discolor the moldings. The commercial value of discolored moldings is low. Combined with such a copper compound, an alkali halide may also be added to the polyamide resin. Examples of the alkali halide are lithium chloride, lithium bromide, lithium iodide, potassium chloride, potassium bromide, potassium iodide, sodium bromide, and sodium iodide. Especially preferred are potassium iodide and sodium iodide.

The PPS resin (b) for use in the invention is a polymer having repetitive units of the following structural formula (I):



From the viewpoint of its heat resistance, the polymer preferably contains at least 70 mol%, more preferably at least 90 mol% of the repetitive units of the structure formula. The PPS resin may contain any other repetitive units such as those mentioned below, within a range smaller than 30 mol% of all the repetitive units that constitute the resin.



The PPS polymer partly having the structure as above will have a lowered melting point. Therefore, in case where the melting point of the thermoplastic resin not in the barrier layer of the multi-layer structure of the invention is low,

the PPS resin of the type is advantageous in point of its moldability.

The melt viscosity of the PPS resin for use in the invention is not specifically defined, so far as the resin can be kneaded in melt. In general, it falls between 50 and 20000 poises (at 320°C at a shear rate of 1000 sec⁻¹), more preferably between 100 and 5000 poises.

The PPS resin of the type can be prepared in any known method, for example, according to the method for preparing polymers having a relatively small molecular weight, described in JP-B 3368/1970; or the method for preparing polymers having a relatively large molecular weight, described in JP-B 12240/1977 and JP-A 7332/1986. Needless-to-say, the PPS resin prepared in the manner as above for use in the invention may be processed in various methods. For example, it may be heated in air for crosslinking it and/or increasing its molecular weight; or may be heated in an inert gas atmosphere such as nitrogen or under reduced pressure; or may be washed with any of organic solvents, hot water or aqueous acid solutions; or may be activated with any of functional group-having compounds such as acid anhydrides, amines, isocyanates and functional group-having disulfide compounds.

One concrete method of heating the PPS resin for crosslinking it and/or increasing its molecular weight comprises heating it in an oxidizing gas atmosphere such as

air or oxygen or in a mixed gas atmosphere comprising the oxidizing gas and an inert gas such as nitrogen or argon, in a container heated at a predetermined temperature so that its melt viscosity reaches the desired level. The temperature for the heat treatment generally falls between 170 and 280°C, but preferably between 200 and 270°C. The time for the heat treatment generally falls between 0.5 and 100 hours, but preferably between 2 and 50 hours. By controlling both the two, the melt viscosity of the resin can reach the desired level. The device for the heat treatment may be any ordinary hot air drier or may be a rotary heating device or a heating device equipped with a stirring blade. For efficiently and more uniformly heating the resin therein, preferred is a rotary heating device or a heating device equipped with a stirring blade.

One concrete method of heating the PPS resin in an inert gas atmosphere such as nitrogen or under reduced pressure comprises heating it in an inert gas atmosphere such as nitrogen or under reduced pressure, at a temperature falling between 150 and 280°C, preferably between 200 and 270°C, for a period of time falling between 0.5 and 100 hours, preferably between 2 and 50 hours. The device for the heat treatment may be any ordinary hot air drier or may be a rotary heating device or a heating device equipped with a stirring blade. For efficiently and more uniformly heating the resin therein,

preferred is a rotary heating device or a heating device equipped with a stirring blade.

Preferably, the PPS resin for use in the invention is deionized. For deionizing it, concretely, the resin may be washed with any of aqueous acid solutions, hot water, or organic solvents. Two or more these treatments may be combined.

One concrete method of washing the PPS resin with an organic solvent is described. The organic solvent to be used for washing the resin is not specifically defined, and may be any and every one not having the function of decomposing the PPS resin. For example, it includes nitrogen-containing polar solvents such as N-methylpyrrolidone, dimethylformamide, dimethylacetamide; sulfoxide or sulfone solvents such as dimethyl sulfoxide, dimethyl sulfone; ketone solvents such as acetone, methyl ethyl ketone, diethyl ketone, acetophenone; ether solvents such as dimethyl ether, dipropyl ether, tetrahydrofuran; halogen-containing solvents such as chloroform, methylene chloride, trichloroethylene, dichloroethylene, dichloroethane, tetrachloroethane, chlorobenzene; alcohol or phenol solvents such as methanol, ethanol, propanol, butanol, pentanol, ethylene glycol, propylene glycol, phenol, cresol, polyethylene glycol; and aromatic hydrocarbon solvents such as benzene, toluene, xylene. Of those organic solvents, preferred are N-methylpyrrolidone, acetone, dimethylformamide, and chloroform. One or more such

organic solvents may be used either singly or as combined. For washing the PPS resin with such an organic solvent, for example, the resin may be dipped in the solvent, optionally stirred or heated therein. The temperature at which the PPS resin is washed with such an organic solvent is not specifically defined, generally falling between room temperature and 300°C or so. The washing efficiency is higher at a higher washing temperature, but, in general, temperatures falling between room temperature and 150°C or so are enough for good washing results. After thus washed with such an organic solvent, the PPS resin is preferably washed a few times with water or warm water to remove the organic solvent remaining in the resin.

One concrete method of washing the PPS resin with hot water is described. For the desired chemical change in the PPS resin washed with hot water, the water to be used is preferably distilled water or deionized water. Concretely, in general, a predetermined amount of the PPS resin is put into a predetermined amount of water, and heated under normal pressure or in a pressure container with stirring. Regarding the ratio of the PPS resin to water, it is desirable that the amount of water is larger than that of the resin. In general, the bath ratio is so selected that at most 200 g of the PPS resin is put in one liter of water.

One concrete method of processing the PPS resin with acid is described. For example, the PPS resin is dipped in acid

or an aqueous solution of acid, optionally stirred or heated. The acid to be used is not specifically defined, so far as it does not decompose the PPS resin. For example, it includes aliphatic saturated monocarboxylic acids such as formic acid, acetic acid, propionic acid, butyric acid; halo-substituted, aliphatic saturated carboxylic acids such as chloroacetic acid, dichloroacetic acid; aliphatic unsaturated monocarboxylic acids such as acrylic acid, crotonic acid; aromatic carboxylic acids such as benzoic acid, salicylic acid; dicarboxylic acids such as oxalic acid, malonic acid, succinic acid, phthalic acid, fumaric acid; inorganic acidic compounds such as sulfuric acid, phosphoric acid, hydrochloric acid, carbonic acid, silicic acid. Of those, preferred are acetic acid and hydrochloric acid. The acid-processed PPS resin is preferably washed a few times with water or warm water for removing the acid or salt remaining in the resin. The water to be used for the washing treatment is preferably distilled water or deionized water not interfering with the desirable chemical change in the acid-processed PPS resin.

The resin composition of the invention may additionally contain any known compatibilizer having the function of improving the miscibility of the polyamide resin (a) and the PPS resin (b) that constitute the resin composition. Examples of the compatibilizer are organosilane compounds such as alkoxysilanes having at least one function group selected from

an epoxy group, an amino group, an isocyanate group, a hydroxyl group, a mercapto group and an ureido group; modified polyolefins such as random, block or graft copolymers of α -olefins, e.g., ethylene or propylene, with at least one compound selected from α,β -unsaturated carboxylic acids, e.g., acrylic acid, methacrylic acid, maleic acid or crotonic acid, or their derivatives, e.g., esters, anhydrides, halides or salts with sodium, potassium, magnesium or zinc; and epoxy group-having olefin copolymers such as those comprising, as the essential ingredients, α -olefins and glycidyl esters of α,β -unsaturated acids, as well as other polyfunctional epoxy compounds. Two or more of these may be combined for use herein.

The thermoplastic resin structure of the invention is characterized by its partial or entire morphology of such that (1) a PPS resin component forms a continuous phase (matrix phase) and a polyamide resin component forms a disperse phase (for example, like a sea-island configuration), or (2) a PPS resin component and a polyamide resin component both form substantially continuous phases (for example, like a sea-sea configuration), or (3) the continuous phase is formed of a polyamide resin component and the disperse phase is formed of a large number of thin, two-dimensional laminae (layers) of a PPS resin component (like a laminar configuration). The shape of the structure is not specifically defined. In different sites of the structure, the morphology (1), (2) or (3) may be

present together, or may appear twice or more. The morphology (1), (2) or (3) can be seen and confirmed through scanning or transmission electronic microscopy.

The blend ratio of the polyamide resin (a) and the PPS resin (b) that constitute the thermoplastic resin structure of the invention is described. In case where the PPS resin component forms a continuous phase (matrix phase) and the polyamide resin component forms a disperse phase in the morphology of the structure (for example, like a sea-island configuration as in Fig. 1), the polyamide resin accounts for from 5 to 80 % by volume and the PPS resin for from 20 to 95 % by volume. Preferably, the polyamide resin accounts for from 55 to 90 % by volume and the PPS resin for from 20 to 45 % by volume. In that case where the amount of the PPS resin component is small, the morphology in which the PPS resin forms a continuous phase can be formed, for example, by suitably controlling the melt viscosity ratio of polyamide resin/PPS resin. The moldings having the morphology have a good balance of wet characteristics and transmission resistance and, when they are used for the barrier layer in multi-layer structures, they also have a good balance of toughness, interlayer adhesiveness, barrier properties and cost. Therefore, they are extremely favorable. More preferably, the blend ratio of the two components is such that the polyamide resin accounts for from 60 to 75 % by volume and the PPS resin for from 25 to 40 % by volume. If the polyamide

resin component (a) is larger than 80 % by volume, the PPS resin component could hardly form the continuous phase characteristic of the resin moldings of the invention, and the object of the invention cannot be attained. On the other hand, if the polyamide resin component (a) is smaller than 5 % by volume, it is unfavorable since the resin moldings could not be tough and the multi-layer structures could not have good interlayer adhesiveness.

In case where the PPS resin component and the polyamide resin component both form substantially continuous phases (matrix phases) in the morphology of the resin structure (for example, like a sea-sea configuration as in Fig. 2), it is important that the melt viscosity and the compatibility of the polyamide resin and the PPS resin are controlled within a composition range of such that the polyamide resin accounts for from 15 to 85 % by volume and the PPS resin for from 15 to 85 % by volume. For embodying the separated morphology in that manner, the blend ratio of the two components is preferably such that the polyamide resin accounts for from 30 to 70 % by volume and the PPS resin for from 30 to 70 % by volume, more preferably such that the polyamide resin accounts for from 35 to 65 % by volume and the PPS resin for from 35 to 65 % by volume. If the polyamide resin component (a) is larger than 85 % by volume, the PPS resin component could hardly form a substantially continuous phase, and structures that attain the object of the

invention could not be obtained.

For forming the morphology in which the polyamide resin component forms a continuous phase (matrix phase) and the PPS resin component forms a large number of thin, two-dimensional laminae (layers) of a disperse phase (a laminar structure as in Fig. 3), the polyamide resin accounts for from 55 to 95 % by volume and the PPS resin for from 5 to 45 % by volume. Preferably, the polyamide resin accounts for from 60 to 95 % by volume and the PPS resin for from 5 to 40 % by volume; more preferably, the polyamide resin accounts for from 65 to 95 % by volume and the PPS resin for from 5 to 35 % by volume. If the polyamide resin component (a) is larger than 95 % by volume, the laminar disperse phase of the PPS resin component could not be prolonged to have a desired length and a desired weight, and the object of the invention cannot be attained. If the polyamide resin component (a) is smaller than 55 % by volume, the PPS resin component could hardly form a laminar disperse phase.

L/T (length/thickness) of the PPS resin component that forms the laminar disperse phase is preferably at least 30. More preferably, L/T is at least 100, even more preferably at least 150. If L/T is smaller than 30, structures having the desired barrier properties could not be obtained. The uppermost limit of L/T is not specifically defined, but is preferably at most 1×10^6 in practical use.

The inorganic filler (c) usable in the invention is not specifically defined, and may be any fibrous, tabular, powdery or granular filler. Concretely, for example, it includes fibrous or whisker fillers such as glass fibers, PAN or pitch-type carbon fibers, metal fibers, e.g., stainless steel fibers, aluminium fibers or brass fibers, organic fibers, e.g., aromatic polyamide fibers, and gypsum fibers, ceramic fibers, asbestos fibers, zirconia fibers, alumina fibers, silica fibers, titanium oxide fibers, silicon carbide fibers, rock wool, potassium titanium whiskers, barium titanate whiskers, aluminium borate whiskers, silicon nitride whiskers; and non-fibrous fillers such as silicates, e.g., wollastonite, sericite, kaolin, mica, clay, bentonite, asbestos, talc, alumina silicate, swellable phyllosilicates, e.g., montmorillonite, synthetic mica, metal compounds, e.g., alumina, silicon oxide, magnesium oxide, zirconium oxide, titanium oxide, iron oxide, carbonates, e.g., calcium carbonate, magnesium carbonate, dolomite, sulfates, e.g., calcium sulfate, barium sulfate, and glass beads, ceramic beads, boron nitride, silicon carbide, calcium phosphate, and silica. Of those fillers, preferred are glass fibers, as well as PAN carbon fibers for electroconductive structures. The type of the glass fibers for use herein is not specifically defined, and may be any ones generally used for reinforcing resin. For example, they may be in any form of long fibers or short fibers of chopped strands

or milled fibers. As combined, two or more different types of fillers mentioned above may be used herein. On its surface, the filler for use in the invention may be pre-treated with a known coupling agent (e.g., silane coupling agent, titanate coupling agent) or with any other surface-treating agent. Swellable phyllosilicates serving as the filler may be pre-treated with an organic onium compound. Thus pre-treated, the filler is preferred, as it enhances the mechanical strength and the barrier properties of the resin structure containing it.

Glass fibers serving as the filler may be coated or bundled with thermoplastic resin such as ethylene/vinyl acetate copolymer or with thermosetting resin such as epoxy resin.

The amount of the inorganic filler (c) to be in the resin composition preferably falls between 0.5 and 200 parts by weight, more preferably between 5 and 200 parts by weight, even more preferably between 10 and 150 parts by weight relative to 100 parts by weight of the total of the polyamide resin (a) and the PPS resin (b) therein.

The multi-layer structure of the invention is formed by laminating different types of resin layers, in which at least one layer (hereinafter referred to as a barrier layer (α)) is formed of the thermoplastic resin structure having the specific morphology as above, or a resin layer (hereinafter referred to as a neighboring layer (β)) differing from the barrier layer

is formed on at least one surface of a layer of the thermoplastic resin structure of the invention having a different composition or morphology (this is also a barrier layer) or the barrier layer. In one preferred embodiment of the multi-layer structure of the invention, an adhesive, co-extrudable resin layer (hereinafter referred to as an adhesive layer (γ)) is suitably formed between the barrier layer (α) and the neighboring layer (β) for enhancing the adhesiveness between the two layers. Concretely, for example, the layer configuration of the multi-layer structure of the type includes a two-resin two-layer configuration of layer (α)/layer (β); a two-resin three-layer configuration of layer (β)/layer (α)/layer (β); a three-resin three-layer configuration of layer (β)/layer (γ)/layer (α); a three-resin four-layer configuration of layer (β)/layer (γ)/layer (α)/layer (β); and a three-resin five-layer configuration of layer (β)/layer (γ)/layer (α)/layer (γ)/layer (β), to which, however, the invention is not limited.

The resin to form the neighboring layer (β) in the multi-layer structure of the invention is a thermoplastic resin of which the morphology and the composition differ from the requirements in the invention. The type of the thermoplastic resin is not specifically defined, and may be any one selected in accordance with the use and the object of the multi-layer structure. Its examples are saturated polyester resins, polysulfone resins, polyethylene tetrafluoride resins,

polyetherimide resins, polyamidimide resins, polyamide resins, polyimide resins, polycarbonate resins, polyether sulfone resins, polyether ketone resins, polythioether ketone resins, polyether-ether ketone resins, thermoplastic polyurethane resins, polyolefin resins, ABS resins, polyamide elastomers, and polyester elastomers. Two or more of these may be combined for use herein. Of those, especially preferred are polyolefin resins, thermoplastic polyester resins, polyamide resins, polycarbonate resins and ABS resins.

Preferred examples of the polyolefin resins are low-, middle- and high-density polyethylene, polypropylene, ethylene/propylene copolymer, poly-1-butene, poly-4-methylpentene-1, polyethylene chloride, chloropolyethylene, chloropolypropylene, and polymethylpentene. Of those, more preferred are low-, middle- and high-density polyethylene, polypropylene, and ethylene/propylene copolymer.

Preferred examples of the thermoplastic polyesters are those obtained from dicarboxylic acids such as terephthalic acid and aliphatic diols. The dicarboxylic acids except terephthalic acid for the polyesters are, for example, aliphatic dicarboxylic acids having from 2 to 20 carbon atoms, such as azelaic acid, sebacic acid, adipic acid, decanedicarboxylic acid; aromatic dicarboxylic acids such as isophthalic acid, naphthalenedicarboxylic acid; and alicyclic dicarboxylic acids

such as cyclohexanedicarboxylic acid. One or more of these may be used either singly or as combined. The aliphatic diols include, for example, ethylene glycol, 1,2-propylene glycol, 1,3-propylene glycol, 1,4-butanediol, trimethylene glycol, 1,4-cyclohexanedimethanol, and hexamethylene glycol. Concretely, the polyesters are polyethylene terephthalate, polypropylene terephthalate, polybutylene terephthalate, polyhexamethylene terephthalate, polycyclohexylenedimethylene terephthalate, and polyethylene naphthalate. Of those, especially preferred for use herein are polybutylene terephthalate of good mechanical strength, and copolyesters that comprise a dicarboxylic acid component containing at least 60 mol%, preferably at least 70 mol% of terephthalic acid along with dodecanedicarboxylic acid and/or isophthalic acid, and a 1,4-butanediol component.

The degree of polymerization of these thermoplastic polyester resins is not specifically defined. For example, polybutylene terephthalate and polybutylene terephthalate copolymer that are preferred for use in the invention are preferably such that the intrinsic viscosity thereof measured in a 0.5 % orthochlorophenol solution at 25°C falls between 0.5 and 2.5, more preferably between 0.8 and 2.0. Polyethylene terephthalate for use herein is preferably such that its intrinsic viscosity measured in a 0.5 % orthochlorophenol solution at 25°C falls between 0.54 and 1.5, more preferably

between 0.6 and 1.2.

Examples of the polyamide resins may be the same as those of the component (a) mentioned hereinabove. Above all, especially preferred are polyamide resins that are so constituted that the number of carbon atoms in one amido group therein falls between 8 and 15. More preferred are polyamide resins derived from a monomer of aminocarboxylic acid or its derivative, as they ensure better low-temperature toughness. Examples of the polyamides of the type include are polydodecanamide (nylon 12) and polyundecanamide (nylon 11), and polyamides having a relative viscosity, measured in metacresol (having a polymer concentration of 0.5 % by weight) at 25°C, of from 1.0 to 7.0, preferably from 1.5 to 5.0.

The degree of polymerization of the polyamide resins is not specifically defined. For example, preferred are those having a relative viscosity of from 1.5 to 7.0, more preferably from 2.0 to 6.5, even more preferably from 2.5 to 5.5, measured in a 98 % concentrated sulfuric acid solution having a sample concentration of 0.01 g/ml at 25°C.

The thermoplastic resins to form the neighboring layer (β) may contain, if desired, additives such as plasticizer, antioxidant, nucleating agent and colorant suitable to the respective resins.

The multi-layer structure of the invention, which has a barrier layer (α) formed of the thermoplastic resin structure

having a separated morphology specifically defined in the invention, and a neighboring layer (β) formed on one or both surfaces of the barrier layer, can be produced, for example, in a two-layer injection molding method. However, the multi-layer structure in the form of a film or sheet may be produced in a coextrusion molding method that comprises melting the layer-forming compositions in separate extruders, feeding the melts into a multilayer-forming die and coextruding them through the die; or in a lamination molding method that comprises separately forming a layer to be the neighboring layer followed by melt-extruding a barrier layer thereon. The multi-layer structure for blow-molding containers such as bottles, barrels or tanks or for tabular articles such as pipes or tubes may be produced in an ordinary coextrusion molding method. For example, two-layered blow moldings of the multi-layer structure, of which the inner layer is a barrier layer having a specific morphology as herein and the outer layer is a neighboring layer, can be produced by separately feeding a resin composition for the barrier layer and a resin composition for the neighboring layer into the respective two extruders, then feeding the two resin melts into a die common thereto under pressure to form the respective circular flows integrated in such a manner that the flow for the barrier layer is inside and the flow for the neighboring layer is outside, then coextruding them out of the die, and working the resulting laminate in an ordinary known

tube-forming or blow-molding method to give the intended two-layered blow moldings. Three-layered blow moldings of the multi-layer structure can be produced in the same manner as above, but using three extruders to form three-layered structures. For these, alternatively, usable are two extruders to form two-resin three-layered blow moldings. Of those methods, preferred is the coextrusion molding method as it ensures good interlayer adhesiveness of the multi-layer structures produced therein.

Preferably, the multi-layer structure of the invention has an adhesive layer (γ) suitably formed between the barrier layer (α) and the neighboring layer (β) for the purpose of further improving the impact resistance, the moldability and the interlayer adhesiveness thereof. The resin to form the adhesive layer is not specifically defined in point of its configuration, so far as it is adhesive to both the barrier layer (α) and the neighboring layer (β) and it is coextrudable with the two layers. Concretely, examples of the resin are modified polyolefins such as random, block or graft copolymers comprising an α -olefin, e.g., ethylene or propylene, and at least one compound selected from α, β -unsaturated carboxylic acids such as acrylic acid, methacrylic acid, maleic acid and crotonic acid, and their derivatives such as esters, anhydrides, halides and salts with sodium, potassium, magnesium or zinc; random, block or graft copolymers comprising an α -olefin such as ethylene or propylene,

and at least one compound selected from vinyl acetate, vinyl alcohol and styrenes; copolyamide adhesives and copolyester adhesives. Depending on the use of the adhesive layer, the multi-layer structure may have different forms of, for example, two-resin two-layer, two-resin three-layer, three-resin three-layer, three-resin four-layer or three-resin five-layer structures.

For making it electroconductive, the thermoplastic resin structure of the invention may contain an electroconductive filler and/or an electroconductive polymer. The additives are not specifically defined. For example, the electroconductive filler may be any and every one generally used in ordinary resins for making them electroconductive. Its examples are metal powders, metal flakes, metal ribbons, metal fibers, metal oxides, electroconductive substance-coated inorganic fillers, carbon powder, graphite, carbon fibers, carbon flakes, and scaly carbon.

Examples of the metal for the metal powders, metal flakes and metal ribbons are silver, nickel, copper, zinc, aluminium, stainless steel, iron, brass, chromium, and tin.

Examples of the metal for the metal fibers are iron, copper, stainless steel, aluminium, and brass.

The metal powders, metal flakes, metal ribbons and metal fibers may be processed on their surfaces with a surface-treating agent such as titanate-type, aluminium-type or silane-type

agents.

Examples of the metal oxides are (antimony-doped) SnO_2 , (antimony-doped) In_2O_3 , and (aluminium-doped) ZnO . These may be processed on their surfaces with a surface-treating agent such as titanate, aluminium or silane coupling agents.

Examples of the electroconductive substance for the electroconductive substance-coated inorganic fillers are aluminium, nickel, silver, carbon, (antimony-doped) SnO_2 , and (antimony-doped) In_2O_3 . Examples of the inorganic fillers to be coated with it are mica, glass beads, glass fibers, carbon fibers, potassium titanate whiskers, barium sulfate, zinc oxide, titanium oxide, aluminium borate whiskers, zinc oxide whiskers, titanium oxide whiskers, and silicon carbide whiskers. For coating them, for example, employable are various methods of vacuum vapor deposition, sputtering, electroless plating or baking. The inorganic fillers may be processed on their surfaces with a surface-treating agent such as titanate, aluminium or silane coupling agents.

Grouped from its starting materials and production methods, carbon powder includes, for example, acetylene black, gas black, oil black, naphthalene black, thermal black, furnace black, lamp black, channel black, roll black, and disc black. The carbon powder for use in the invention is not specifically defined in point of its starting materials and production methods. For it, however, especially preferred are acetylene black and

furnace black. Produced are various types of carbon powder that differ in their characteristic parameters such as particle size, surface area, DBP oil absorption and ash content. The carbon powder for use in the invention is not specifically defined in point of its characteristic parameters. However, for good balance of strength and electroconductivity thereof, the carbon powder for use herein preferably has a mean particle size of at most 500 nm, more preferably falling between 5 and 100 nm, even more preferably between 10 and 70 nm. The specific surface area (in BET method) of the carbon powder is preferably at least 10 m²/g, more preferably at least 30 m²/g. The DBP oil absorption thereof is preferably at least 50 ml/100 g, more preferably at least 100 ml/100 g. The ash content thereof is preferably at most 0.5 % by weight, more preferably at most 0.3 % by weight.

The carbon particles may be processed on their surfaces with a surface-treating agent such as titanate-type, aluminium-type or silane-type agents. For better processability in melt kneading, the carbon powder may be formed into granules.

Depending on their use, the moldings of the invention are desired to have good surface smoothness. From this viewpoint, desired for the electroconductive fillers for use in the invention are powdery, granular, tabular or flaky matters as well as fibrous matters that have a ratio of length/diameter

of at most 200 in the resin composition, rather than fibrous fillers having a high aspect ratio, like those for the inorganic filler (c) used in the invention.

Examples of the electroconductive polymer are polyaniline, polypyrrole, polyacetylene, poly(paraphenylene), polythiophene, and polyphenylenevinylene.

Two or more different matters of the electroconductive filler and/or the electroconductive polymer may be used herein, as combined. Of those electroconductive fillers and electroconductive polymers, especially preferred is carbon black as it is strong and inexpensive.

The content of the electroconductive filler and/or the electroconductive polymer that may be in the resin structure of the invention varies, depending on the type of the electroconductive filler and/or the electroconductive polymer to be used, and therefore could not be indiscriminately defined. However, from the viewpoint of the balance of the electroconductivity, the flowability and the mechanical strength of the resin composition, it is desirable that the filler content of the resin composition falls between 1 and 250 parts by weight, more preferably between 3 and 100 parts by weight relative to 100 parts by weight of the total of the components (a), (b) and (c). Also more preferably, the filler content falls between 3 and 100 parts by weight relative to 100 parts by weight of the total of the components (a) and (b)

for well making the resin structure electroconductive.

Preferably, the electroconductive resin structure has a volume resistivity of at most $10^{10} \Omega \cdot \text{cm}$ in order that it is resistant to static electrification. However, the electroconductive filler and the electroconductive polymer, if any in the resin composition, will often worsen the flowability of the composition and the strength of the resin structure. Therefore, so far as the intended electroconductive level is attained, the amount of the electroconductive filler and the electroconductive polymer to be in the resin composition is as small as possible. The intended electroconductive level varies, depending on the use of the resin structure. In general, the volume resistivity of the resin structure shall be larger than $100 \Omega \cdot \text{cm}$ but not larger than $10^{10} \Omega \cdot \text{cm}$.

The resin composition of the invention may contain any other components not detracting from the effect of the invention. For example, it may contain any of antioxidants and heat-resistant stabilizers (e.g., hindered phenols, hydroquinones, phosphites and their substituted derivatives), weatherproofing agents (e.g., resorcinols, salicylates, benzotriazoles, benzophenones, hindered amines), mold release agents and lubricants (e.g., montanic acid and its metal salts, esters and half esters; stearyl alcohol, stearamide, various bisamides, bisureas, polyethylene wax), pigments (e.g., cadmium sulfide, phthalocyanine, carbon black), dyes (e.g.,

nigrosine), nucleating agents (e.g., talc, silica, kaolin, clay), plasticizers (e.g., octyl p-hydroxybenzoate, N-butylbenzenesulfonamide), antistatic agents (e.g., alkylsulfate-type anionic antistatic agents, quaternary ammonium-type cationic antistatic agents, nonionic antistatic agents such as polyoxyethylene sorbitan monostearate, betaine-type ampholytic antistatic agents), flame retardants (e.g., red phosphorus, melamine cyanurate, hydroxides such as magnesium hydroxide and aluminium hydroxide, ammonium polyphosphate, polystyrene bromide, polyphenylene ether bromide, polycarbonate bromide, epoxy bromide resin, and combinations of such a bromine-containing flame retardant and antimony trioxide), and other polymers.

The method for producing the resin structure of the invention is not specifically defined, so far as the resin structure produced can have the morphology that satisfies the requirement of the invention. For example, the polyamide resin and the PPS resin to form the resin structure are fed into separate two extruders through the respective main feeders and an inorganic filler is added thereto through a side feeder disposed at the top of each extruder; or the polyamide resin and the PPS resin are first kneaded in melt, and an inorganic filler is added to the mixed resin melt.

The thermoplastic resin structure and the multi-layer structure of the invention may be shaped in any known manner,

and the method of molding them is not specifically defined, for which, for example, employable is injection molding, extrusion molding, blow molding or press molding. Especially preferred for molding them is at least one method selected from injection molding, injection compression molding and compression molding for enhancing the productivity and the industrial application of the invention. The molding temperature may fall generally within a range higher than the melting point of the PPS resin by from 5 to 50°C. In general, the moldings are single-layered, but may be multi-layered in a two-layer molding method.

The layer configuration in the multi-layer structure of the invention is not specifically defined. All the layers of the multi-layer structure may be formed of the thermoplastic resin structure of the invention, or any other thermoplastic resin may be used for some layers. In two or more multi-layered multi-layer structures, the layer of the thermoplastic resin structure of the invention is preferably the innermost layer in order that it can fully exhibit its transmission-resistant effect. The moldings obtained herein may be integrated together or with other moldings by the use of an adhesive or through hot-sealing, and the method of integrating them is not specifically defined, for which are employable any known techniques.

As the thermoplastic resin structure and the multi-layer

structure of the invention have good gas barrier properties, and are durable and easy to work, they are favorable for containers for transportation and/or storage of liquid chemicals and gases, for the attached parts of such containers, and also for multi-layered tubes or multi-layered blow moldings to be formed through coextrusion. Regarding the liquid chemicals and the gases, the resin structure and the multi-layer structure are highly resistant to transmission therethrough of vapors and/or liquids and also evaporated gases, for example, Flon-11, Flon-12, Flon-21, Flon-22, Flon-113, Flon-114, Flon-115, Flon-134a, Flon-32, Flon-123, Flon-124, Flon-125, Flon-143a, Flon-141b, Flon-142b, Flon-225, Flon-C318, R-502, 1,1,1-trichloroethane, methyl chloride, methylene chloride, ethyl chloride, methylchloroform, propane, isobutane, n-butane, dimethyl ether, castor oil-based brake fluid, glycol ether-based brake fluid, borate-based brake fluid, brake fluid for use in extremely cold regions, silicone oil-based brake fluid, mineral oil-based brake fluid, power steering oil, windshield wash, gasoline, methanol, ethanol, isobutanol, butanol, nitrogen, oxygen, hydrogen, carbon dioxide, methane, propane, natural gas, argon, helium, xenon and medicines. Therefore, the resin structure and the multi-layer structure have many applications for parts of electric and electronic appliances, medical appliances, food-related appliances, household and office-use appliances, constructions-related

parts, furniture parts and others. For example, their applications are for films of transmission resistance against vapors and/or liquids mentioned above; as well as for tanks and bottles for automobile parts, parts for medical appliances and daily commodities, such as air bags, bottles for liquid chemicals such as shampoo, rinse, liquid soap, detergent, tanks for storage of liquid chemicals, tanks for storage of gases, coolant tanks, oil transportation tanks, disinfectant tanks, tanks for blood transfusion pumps, fuel tanks, windshield wash tanks, oil reservoir tanks, canisters; Attached parts for such tanks and bottles, such as valves, e.g., cutoff valves, joints, gauges for attendant pumps, cases and other parts, various fuel tubes and connecting parts (e.g., connectors), e.g., fuel filler under-pipes, ORVR hoses, reserve hoses, bent hoses, oil tubes and connecting parts, brake hoses and connecting parts, windshield wash nozzles and hoses, cooler hoses and connecting parts for cooling water and coolant, tubes and connecting parts for coolant for air conditioners, floor-warming pipes and connecting parts, fire extinguishers and fire hoses, tubes, connecting parts and valves for medical cooling devices, tubes for transportation of liquid chemicals and gases, containers for storage of liquid chemicals, and other applications requiring liquid chemical and vapor transmission resistance; and machine parts such as automobile parts, internal combustion engine parts, and housings for electric tools.

EXAMPLES

The invention is described in detail hereinunder with reference to Examples. However, the scope of the invention is not limited to only the following Examples.

(1) Alcohol gasoline transmission:

Using a 40 mm ϕ extruder with a tubular die, a sizing die to cool the tube extruded out of the extruder and to control the size of the tube and a take-up unit disposed at its top, a tube having an outer diameter of 8 mm and an inner diameter of 6 mm was molded. The tube was cut into a length of 20 cm. One end of the sample was sealed up, just 6 g of an alcohol gasoline mixture of commercially-available regular gasoline/ethanol of 75/25 by weight was put into it, and the other end thereof was sealed up. With that, the overall weight of the sample was measured. The sample was put into an explosion-proof oven at 60°C, and kept therein for 500 hours, and its weight loss was measured.

(2) Alcohol gasoline transmission in wet:

The test tube filled with the alcohol gasoline mixture in the same manner as in the above (1) was kept in a thermo-hygrostat at 40°C and 65 % RH for 500 hours, and its weight loss was measured.

(3) Oxygen transmission:

Measured according to JIS K7176, method A (differential

pressure method), for which used was GTR-10 (by Yanako Bunseki Kogyo).

(4) Mechanical strength:

Measured according to standard methods mentioned below.

Tensile strength: ASTM D638

Flexural modulus: ASTM D790

Izod impact strength: ASTM D256

(5) Water absorption:

Test pieces of ASTM #1 (thickness, 1/8 inches) were prepared. They were kept in a thermo-hygrostat at 60°C and 95 % RH for 24 hours. The weight increase in wet was obtained from the absolute dry weight of the test piece just after prepared and the wet weight thereof after wetted.

Water absorption (%) = $\{(\text{wet weight} - \text{absolute dry weight}) / (\text{absolute dry weight})\} \times 100$.

(6) Dimensional stability in wet:

The test pieces were wetted in the same manner as in the test for water absorption. The length increase in wet was obtained from the length (in the machine direction) of the dry test piece just after prepared and the length of the wetted test piece.

Dimensional stability in wet (%) = $\{(\text{length of wetted test piece} - \text{length of dry test piece}) / (\text{length of dry test piece})\} \times 100$.

(7) Flexural modulus in wet:

The flexural modulus of the test piece wetted in the same manner as in the test for water absorption was measured according to ASTM D790.

(8) Analysis of separated morphology:

The cross section (barrier layer) of the molded tube was analyzed with electronic microscopes (TEM, SEM).

(9) Melt viscosity ratio:

Using a plunger-type capillary rheometer, the melt viscosity (poise) of the resin sample was measured at its melt-kneading temperature at a shear rate of 10 sec^{-1} .

Melt viscosity ratio = (melt viscosity of polyamide resin) / (melt viscosity of PPS resin).

(10) Physical properties of multi-layer structure:

(A) Gasohol barrier properties:

The tube was cut into a length of 30 cm. One end of the sample was sealed up, an alcohol gasoline mixture of commercially-available regular gasoline/methyl alcohol of 85/15 (by weight) was put into it, and the other end thereof was sealed up. With that, the overall weight of the sample was measured. The sample was put into an explosion-proof oven at 40°C . From the weight change of the sample, the alcohol gasoline transmission through the tube was determined.

(B) Interlayer adhesion strength:

The tube was cut and opened into a rectangular strip having a width of 10 mm, and the inner and outer layers with an adhesive

layer therebetween (the adhesive layer was stuck to the neighboring layer (β) of a thermoplastic resin composition) were peeled away by pulling them in the opposite directions at 180 degrees, whereupon the adhesion strength per the unit length of the sample was measured.

[Reference Example 1 (preparation of PPS copolymer)]

3.26 kg of sodium sulfide (25 mols, containing 40 % crystal water), 4 g of sodium hydroxide, 1.36 kg of sodium acetate trihydrate (about 10 mols), and 7.9 kg of N-methylpyrrolidone were fed into an autoclave equipped with a stirrer, and gradually heated up to 205°C with stirring, and about 1.5 liters of distillate containing 1.36 kg of water was removed. To the residual mixture, added were 3.38 kg of 1,4-dichlorobenzene (23.0 mols), 0.37 kg of 1,3-dichlorobenzene (2.5 mols), and 2 kg of NMP, and heated at 265°C for 5 hours. The reaction product was washed three times with hot water at 70°C, then with aqueous acetic acid solution with pH = 4 at 60°C, and further four times with hot water at 70°C, and then dried under reduced pressure at 80°C for 24 hours to obtain about 2 kg of a PPS copolymer resin having a melting point of 255°C and a melt flow rate (MFR) of 800 g/10 min (at 315°C under 5000 g).

[Reference Example 2 (preparation of organophyllosilicate)]

100 g of Na-type montmorillonite (Kunipia F by Kunimine Industry, having a cation exchange capacity of 120 meq/100 g) was dispersed in 10 liters of warm water with stirring, to which

was added 2 liters of warm water containing 48 g of trioctylmethylammonium chloride (1 equivalent to the cation exchange capacity) dissolved therein, and stirred for 1 hour. The precipitate formed was taken out through filtration, and washed with warm water. The washing and filtering operation was repeated three times, and the resulting solid was dried in vacuum at 80°C to obtain a dried, organophyllosilicate. The inorganic ash content of the organophyllosilicate was 67 % by weight. It was measured as follows: 0.1 g of the organophyllosilicate was ashed in an electric furnace at 500°C for 3 hours, and the weight change before and after the ashing was measured.

The polyamide resins and PPS used in Examples and Comparative Examples are mentioned below. Unless otherwise specifically indicated, they were prepared through ordinary polymerization.

<Polyamide Resins>

(N6-1): nylon 6 resin having melting point of 225°C and relative viscosity of 2.80.

(N6-2): nylon 6 resin having melting point of 225°C and relative viscosity of 3.30.

(N6-3): nylon 6 resin having melting point of 225°C and relative viscosity of 3.40.

(N6-4): nylon 6 resin having melting point of 225°C and relative viscosity of 4.30.

(N6-5): phyllosilicate-containing nylon 6 resin prepared by mixing 100 parts by weight of nylon 6 resin having melting point of 225°C and relative viscosity of 3.40 and 5 parts by weight of the organophyllosilicate prepared in Reference Example 2, followed by melt-extruding the resulting mixture through a double-screw extruder at a cylinder temperature of 250°C.

(N66): nylon 66 resin having melting point of 265°C and relative viscosity of 3.20.

(N6/66): nylon 6/66 copolymer having melting point of 217°C and relative viscosity of 2.85.

(6T/12): nylon 6T/12 copolymer having melting point of 300°C and relative viscosity of 2.50.

<PPS Resins>

(PPS-1): PPS resin having melting point of 280°C, melt flow rate (MFR) of 1000 g/10 min (at 315°C under 5000 g) and weight-average molecular weight (Mw) of 30000.

(PPS-2): PPS resin having melting point of 280°C, MFR of 300 g/10 min, Mw of 49000 and viscosity of 700 poises.

(PPS-3): PPS resin having melting point of 280°C, MFR of 100 g/10 min, Mw of 70000 and viscosity of 1700 poises.

(PPS-4): PPS resin having melting point of 280°C, MFR of 600 g/10 min, Mw of 38000 and viscosity of 450 poises.

(PPS-5): PPS copolymer resin prepared in Reference Example 1, having melting point of 255°C and MFR of 800 g/10 min.

<Thermoplastic resins except resin compositions to form barrier

layer (these are for neighboring layer)>

(β -1): high-density polyethylene having MFR of 0.3 g/10 min and density of 0.945.

(β -2): polybutylene terephthalate (Toray's LUMI CON 5201X11).

(β -3): nylon 11 (Toray's RILSAN BESN O P40TL).

<Resins for adhesive Layer>

(γ -1): ethylene/glycidyl methacrylate (94/6 wt.%) copolymer.

(γ -2): ethylene/methyl acrylate/glycidyl methacrylate (64/30/6 wt.%) copolymer.

Examples 1 to 12, Comparative Examples 1 to 4:

As in Tables 1 and 2, the polyamide resin and the PPS resin were mixed and fed into a double-screw extruder, Nippon Seikosho's TEX 30 Model through its main feeder. The inorganic filler, if used, was fed thereinto through a side feeder provided at some part of the cylinder. These were kneaded in melt in the extruder at 300°C, for which the screw revolution was 200 rpm. The resulting pellets were dried, and then injection-molded into test pieces. The injection-molding machine used was Toshiba Kikai's IS100FA, and the mold temperature was 80°C. In addition, the pellets prepared in the same manner as above were molded into tubes for the test for alcohol gasoline transmission through them. The data of the transmission resistance, the mechanical strength and the physical properties in wet of the samples are given in Tables 1 and 2.

In the Tables, GF is glass fibers (of 3 mm chopped strands having a fiber diameter of 10 μm , by Nippon Electric Glass); MF is milled fibers (having a mean fiber length of 140 μm and a mean fiber diameter of 9 μm , by Nippon Electric Glass); and PA is polyamide resin.

Table 1

	Item	Unit	Ex. 1	Ex. 2	Ex. 3	Ex. 4	Ex. 5	Ex. 6	Co. Ex. 1	Co. Ex. 2
Constituent Components	Type of polyamide resin amount	-	N6-2 70	N6-2 60	N6-2 90	N66 70	N6/66 70	N6-2 35	N6-1 100	N6-1 70
	Type of PPS resin amount	-	PPS-1 30	PPS-2 40	PPS-1 10	PPS-1 30	PPS-1 30	PPS-2 65	-	PPS-2 30
	Polyamide/PPS melt viscosity ratio (kneading temperature, °C)	vol.%	5.5 (300)	3.6 (300)	5.5 (300)	4.7 (300)	1.8 (300)	3.6 (300)	-	0.6 (300)
Separated Morphology		continuous phase	PPS	PPS & PA	PA	PPS	PPS & PA	PPS & PA	PA	PA
		disperse phase	PA	-	PPS laminar dispersion	PA	-	-	-	PPS spherical dispersion
			0.2	0.4	0.6	0.3	0.4	0.1	1.7	1.5
Transmission Resistance	Alcohol Gasoline Transmission	g	0.2	0.4	0.6	0.3	0.4	0.1	1.7	1.5
	Alcohol Gasoline Transmission in wet	g	0.4	0.8	1.1	0.7	0.6	0.3	1.9	1.6
	Oxygen Transmission	note 1	10	10	25	10	20	5	50	45
Mechanical Strength	Tensile Strength	MPa	70	75	82	84	73	71	72	66
	Flexural Modulus	GPa	2.9	3.0	3.3	2.9	2.8	3.1	2.9	2.8
	Izod Impact Strength	J/m	49	45	55	51	52	43	54	28
Properties in wet	Water Absorption	%	1.3	0.9	3.0	1.2	1.4	0.3	3.9	2.1
	Dimensional Stability	%	0.04	0.06	0.65	0.05	0.06	0.01	0.58	0.19
	Flexural Modulus	GPa	1.7	2.0	1.1	1.8	1.6	2.2	0.6	1.1

(N6-1): nylon 6 resin with m.p. 225°C and relative viscosity 2.80.
 (N6-2): nylon 6 resin with m.p. 225°C and relative viscosity 3.30
 (N66): nylon 66 resin with m.p. 265°C and relative viscosity 3.20.
 (N6/66): nylon 6/66 copolymer with m.p. 217°C and relative viscosity 2.85.
 (PPS-1): PPS resin with m.p. 280°C, MFR 1000 g/10 min, and Mw 30000.
 (PPS-2): PPS resin with m.p. 280°C, MFR 300 g/10 min, and Mw 49000.

Table 2

	Item	Unit	Ex. 7	Ex. 8	Ex. 9	Ex. 10	Ex. 11	Ex. 12	Co. Ex. 3	Co. Ex. 4
Constituent Components	Type of polyamide resin amount	-	N6-2 70	N6-2 60	N6-1 75	N66 70	N6/66 70	N6-2 35	N6-1 100	N6-1 70
	Type of PPS resin amount	vol. %	PPS-1 30	PPS-2 40	PPS-1 25	PPS-1 30	PPS-1 30	PPS-2 65	-	PPS-2 30
	Type of Inorganic Filler amount	-	GF 40	GF 40	GF 40	GF/Italc 35/5	GF/MF 30/10	GF 40	GF 40	GF 40
	Polyamide/PPS melt viscosity ratio (kneading temperature, °C)	vol. %	5.5 (300)	3.6 (300)	1.6 (300)	4.7 (300)	1.8 (300)	3.6 (300)	-	0.6 (300)
Separated Morphology		continuous phase	PPS	PPS & PA	PA	PPS	PPS & PA	PPS & PA	PA	PA
		disperse phase	PA	-	PPS laminar dispersion	PA	-	-	-	PPS spherical dispersion
Transmission Resistance	Alcohol Gasoline Transmission	g	0.2	0.3	0.3	0.3	0.3	0.1	1.5	1.4
	Alcohol Gasoline Transmission in wet	g	0.5	0.7	0.7	0.6	0.6	0.3	1.7	1.6
	Oxygen Transmission	note 1	10	10	15	10	20	5	50	45
	Tensile Strength	MPa	165	150	175	170	165	135	185	160
Mechanical Strength	Flexural Modulus	GPa	9.2	9.5	9.0	9.3	9.0	9.5	8.5	9.0
	Izod Impact Strength	J/m	100	90	110	100	105	90	110	85
	Water Absorption	%	0.7	0.6	0.9	0.6	0.7	0.3	3.0	1.5
Properties in wet	Dimensional Stability	%	0.03	0.02	0.03	0.03	0.03	0.01	0.13	0.05
	Flexural Modulus	GPa	7.0	7.4	6.5	7.3	6.9	8.6	4.0	5.5

(N6-1): nylon 6 resin with m.p. 225°C and relative viscosity 2.80.

(N6-2): nylon 6 resin with m.p. 225°C and relative viscosity 3.30

(N66): nylon 66 resin with m.p. 265°C and relative viscosity 3.20.

(N6/66): nylon 6/66 copolymer with m.p. 217°C and relative viscosity 2.85.

(PPS-1): PPS resin with m.p. 280°C, MFR 1000 g/10 min, and Mw 30000.

(PPS-2): PPS resin with m.p. 280°C, MFR 300 g/10 min, and Mw 49000.

As in Examples 1 to 12 and Comparative Examples 1 to 4, the resin moldings of the invention having a specific, separated morphology as defined herein have good transmission resistance, and especially when wetted, their transmission resistance, dimensional stability and stiffness are good and well balanced, and they confirmed the practical applicability of the resin structure of the invention. In addition, the test pieces formed through injection moldings also have good transmission resistance and confirmed the practical applicability of the resin structure of the invention.

Examples 13 to 21, Comparative Examples 5 to 7:

As in Tables 3 and 4, the polyamide resin and the PPS resin were mixed with an organosilane compound (γ -glycidoxypropyltrimethoxysilane) for a barrier layer, and the resulting mixture was fed into a double-screw extruder, Nippon Seikoshō's TEX 30 Model, and kneaded in melt at 270 to 300°C, for which the screw revolution was 200 rpm. The resulting pellets were dried, and then molded into tubes.

In that manner, molded were three-resin three-layer tubes composed of one barrier layer (α), one neighboring layer (β) of thermoplastic resin, and one adhesive layer (γ) between the barrier layer and the neighboring layer. For these, the molding machine used has three extruders, a forming die, a sizing die and a take-up unit, in which the resin melts extruded out of the three extruders are collected in an adapter and molded into

a tube through the forming die, and the tube is cooled and its size is controlled by the sizing die.

The three-layer tubes obtained herein had an outer diameter of 8 mm and an inner diameter of 6 mm, in which the thickness of the outer layer (thermoplastic resin layer) was 0.70 mm, that of the adhesive layer was 0.10 mm and that of the inner layer (barrier layer) was 0.20 mm. The multi-layer tubes were tested, and the test results are given in Tables 3 and 4. Some of them were analyzed through electronic microscopy, and their electronmicroscopic pictures showing the separated morphology are presented herewith as Figs. 4 to 7.

Table 3

Constituent Components of Barrier Layer (α)		Item	Unit	Ex. 13	Ex. 14	Ex. 15	Co. Ex. 5	Co. Ex. 6	Co. Ex. 7
	Type of polyamide resin (a)	Amount of polyamide resin	-	N6-4	N6-3	N6-4	-	N6-3	N6-4
	65		70	75		65	100		
	Type of PPS resin (b)	Amount of PPS resin	-	PPS-4	PPS-4	PPS-3	PPS-3	PPS-3	-
	35		30	25	100	35			
	Organosilane compound	wt.pts.	0.8	0.6	0.4	-	0.8	-	
Layer (β)	Melt Viscosity Ratio of polyamide resin/PPS resin (kneading temperature, °C)		7.0	2.5	1.1	-	0.4	-	
		(300)	(300)	(300)					
Layer (γ)	Thermoplastic resin layer (neighboring layer)		β-1	β-1	β-1	β-1	β-1	β-1	β-1
Separated Morphology of Barrier Layer	Adhesive layer		γ-1	γ-1	γ-1	γ-1	γ-1	γ-1	γ-1
	continuous phase		PPS	PPS and PA	PA	PPS	PPS	PA	PA
		disperse phase		PA	-	PPS laminar dispersion	-	PPS spherical dispersion	-
Gasohol Barrier Properties	gasohol transmission (g·mm/m ² ·24 h·atm)		0.38	0.41	0.48	0.24	4.12	5.70	
Interlayer Adhesion Strength of Moldings (kg/10 mm)			2.4	2.8	3.4	0.5 or less	4.2	5.6	

(N6-3): nylon 6 resin with m.p. 225°C and relative viscosity 3.40.
 (N6-4): nylon 6 resin with m.p. 225°C and relative viscosity 4.30.
 (PPS-3): PPS resin with m.p. 280°C, MFR 100 g/10 min, and Mw 70000.
 (PPS-4): PPS resin with m.p. 280°C, MFR 600 g/10 min, and Mw 38000.
 (β -1): high-density polyethylene with MFR 0.3 g/10 min, and density 0.945.
 (γ -1): ethylene/glycidyl methacrylate copolymer.

Table 4

Constituent Components of Barrier Layer (α)	Item	Unit	Ex. 16	Ex. 17	Ex. 18	Ex. 19	Ex. 20	Ex. 21
			N6-4 40	N6-5 65	N6-5 60	6T/12 65	N6-4 70	N6-3 65
Layer (β)	Type of polyamide resin (a) Amount of polyamide resin	vol. %	PPS-4 60	PPS-5 35	PPS-4 40	PPS-4 35	PPS-3 30	PPS-5 35
	Type of PPS resin (b) Amount of PPS resin	vol. %	0.8	0.8	0.6	0.8	0.6	0.8
	Organosilane compound	wt. pts.	7.0 (300)	9.5 (270)	10.0 (300)	2.4 (320)	1.1 (300)	9.5 (270)
	Melt Viscosity Ratio of polyamide resin/PPS resin (kneading temperature, °C)		β -1	β -1	β -1	β -1	β -2	β -3
Layer (γ)	Thermoplastic resin layer (neighboring layer)		γ -1	γ -1	γ -1	γ -1	γ -2	γ -2
Separated Morphology of Barrier Layer	Adhesive layer		PPS	PPS	PPS	PPS & PA	PA	PPS
			PA	PA	PA	-	PPS laminar dispersion	PA
Gasohol Barrier Properties	gasohol transmission (g·mm/m ² ·24 h·atm)		0.37	0.37	0.30	0.32	0.41	0.29
Interlayer Adhesion Strength of Moldings (kg/10 mm)			2.0	3.7	2.6	2.5	4.0	4.5

(N6-3): nylon 6 resin with m.p. 225°C and relative viscosity 3.40.
 (N6-4): nylon 6 resin with m.p. 225°C and relative viscosity 4.30.
 (N6-5): phyllosilicate-containing nylon 6 resin.
 (6T/12): nylon 6T/12 copolymer with m.p. 300°C and relative viscosity 2.50
 (PPS-3): PPS resin with m.p. 280°C, MFR 100 g/10 min, and Mw 70000.
 (PPS-4): PPS resin with m.p. 280°C, MFR 600 g/10 min, and Mw 38000.
 (PPS-5): PPS copolymer resin with m.p. 255°C, and MFR 800 g/10 min.
 (β -1): high-density polyethylene with MFR 0.3 g/10 min, and density 0.945.
 (β -2): polybutylene terephthalate.
 (β -3): nylon 11.
 (γ -1): ethylene/glycidyl methacrylate copolymer.
 (γ -2): ethylene/methyl acrylate/glycidyl methacrylate copolymer.

The multi-layer structures obtained in Examples 13 to 21, which have a separated morphology defined in the invention, have good gasohol barrier properties and good interlayer adhesiveness, and their practical applicability is good. In addition, the structures obtained in these Examples were fabricated into multi-layer blow moldings, and they had good properties.

INDUSTRIAL APPLICABILITY

The thermoplastic resin structure of the invention has good vapor and/or liquid barrier properties, and, even in high-humidity condition, its transmission resistance and stiffness are still good, and it has many applications in various fields. For example, it is favorable for electric and electronic appliances-related devices, precision machines-related devices, office-use appliances, automobiles and trains-related parts, building materials, wrapping and packaging materials, furniture, and daily necessities. In addition, the multi-layer structure of the invention has good barrier properties against gasohol, and gives plastic containers and tubes having the advantages of strength, durability and workability. It is favorable for gasoline tanks for automobiles, containers and pipes for transportation and storage of liquid chemicals, and wrapping and packaging materials and containers for foods and medicines.

CLAIMS

1. A thermoplastic resin structure formed of a resin composition that comprises substantially (a) from 5 to 80 % by volume of a polyamide resin and (b) from 20 to 95 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, the polyphenylene sulfide resin (b) forms a matrix phase (continuous phase) and the polyamide resin (a) forms a disperse phase.

2. The thermoplastic resin structure as claimed in claim 1, for which the blend ratio of the polyamide resin (a) and the polyphenylene sulfide resin (b) is such that the former accounts for from 55 to 80 % by volume and the latter for from 20 to 45 % by volume.

3. The thermoplastic resin structure as claimed in claim 1, for which the blend ratio of the polyamide resin (a) and the polyphenylene sulfide resin (b) is such that the former accounts for from 60 to 75 % by volume and the latter for from 25 to 40 % by volume.

4. A thermoplastic resin structure formed of a resin composition that comprises (a) from 15 to 85 % by volume of a polyamide resin and (b) from 15 to 85 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, both the phase of the polyphenylene sulfide resin (b) and the phase of the polyamide resin (a) are substantially continuous phases.

5. A thermoplastic resin structure formed of a resin composition that comprises (a) from 55 to 95 % by volume of a polyamide resin and (b) from 5 to 45 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, the polyamide resin (a) forms a continuous phase and the polyphenylene sulfide resin (b) forms a laminar disperse phase.

6. The thermoplastic resin structure as claimed in any of claims 1 to 5, which contains (c) from 0.5 to 200 parts by weight of an inorganic filler relative to 100 parts by weight of the total of the polyamide resin (a) and the polyphenylene sulfide resin (b).

7. Moldings of the thermoplastic resin structure of any of claims 1 to 6, which are formed in at least one method of injection molding, injection compression molding or compression molding.

8. Containers for transportation or storage of liquid chemicals or gases, which are obtained by working the thermoplastic resin structure of any of claims 1 to 7.

9. Attached parts for containers for transportation or storage of liquid chemicals or gases, which are obtained by working the thermoplastic resin structure of any of claims 1 to 7.

10. A multi-layer structure with a barrier layer, in which the barrier layer is formed of the thermoplastic resin structure of any of claims 1 to 6.

11. The multi-layer structure as claimed in claim 10, wherein a neighboring layer is formed on one or both surfaces of the barrier layer, and the neighboring layer is a thermoplastic resin layer differing from the thermoplastic resin structure that forms the barrier layer.

12. The multi-layer structure as claimed in claim 11, wherein the thermoplastic resin to form the neighboring layer is at least one selected from polyolefin resins, thermoplastic polyester resins, polyamide resins, polycarbonate resins and ABS resins.

13. The multi-layer structure as claimed in claim 11, wherein the thermoplastic resin to form the neighboring layer is high-density polyethylene.

14. The multi-layer structure as claimed in claim 11, which has an adhesive layer formed between the barrier layer and the neighboring layer.

15. The multi-layer structure as claimed in any of claims 10 to 14, which is formed through coextrusion.

16. The multi-layer structure as claimed in any of claims 10 to 15, which is formed into multi-layered tubes or multi-layered blow moldings through coextrusion.

ABSTRACT

Provided is a thermoplastic resin structure formed of a resin composition that comprises substantially (a) from 5 to 80 % by volume of a polyamide resin and (b) from 20 to 95 % by volume of a polyphenylene sulfide resin, which is characterized in that, in morphology therein seen through electronic microscopy, the polyphenylene sulfide resin (b) forms a matrix phase (continuous phase) and the polyamide resin (a) forms a disperse phase. The gives plastic containers, tubes and their Attached parts having good barrier properties, strength, durability and workability.

Fig. 1

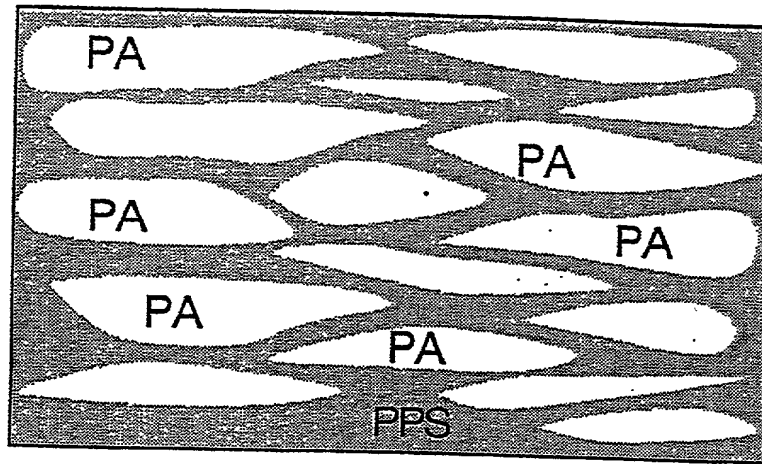


Fig. 2

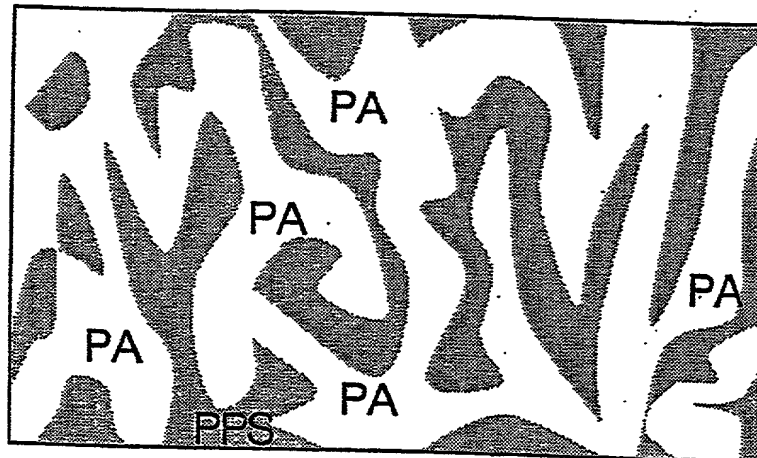


Fig. 3

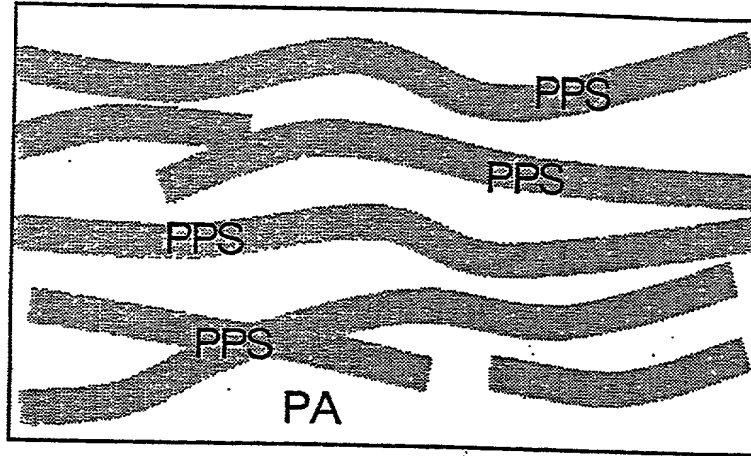


Fig. 4

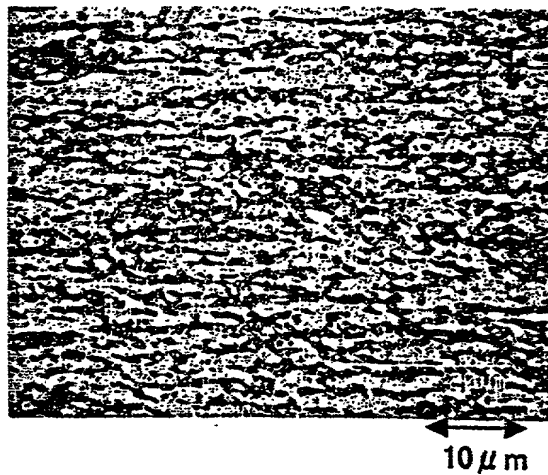


Fig. 4 - Separated Morphology in Example 13

Fig. 5

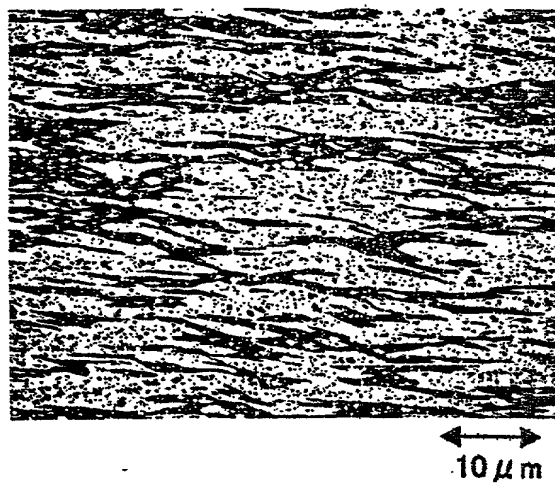


Fig. 5 - Separated Morphology in Example 14

Fig. 6

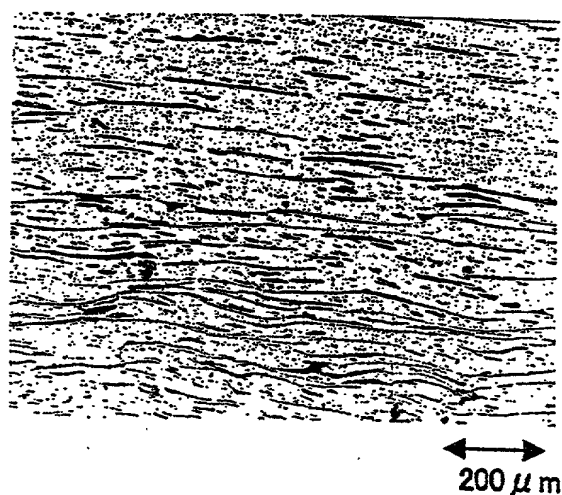


Fig. 6 - Separated Morphology in Example 15

Fig. 7

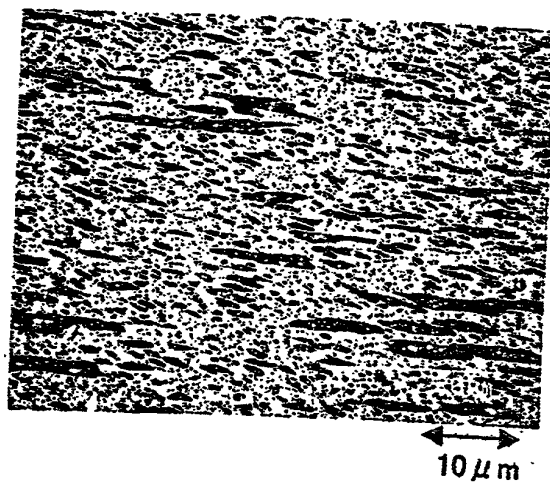


Fig. 7 - Separated Morphology in Comparative Example 5

Attorney Docket No. 1098-02

- ☐ Original Application
☒ PCT National Application
U.S. Designated Office
☐ Continuation or Divisional Application
☐ Continuation-in-Part Application

**COMBINED DECLARATION,
POWER OF ATTORNEY AND PETITION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled RESIN STRUCTURES AND THEIR USE

which is described in the specification and claims

☐ attached hereto.

☐ filed on _____

Application Serial No. _____

and was amended on _____

(if applicable)

☒ which is described in International Application No. **PCT/JP00/06750**

filed on **September 29, 2000** and as amended on _____

_____ (if any),
which I have reviewed and for which I solicit a United States patent.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I do not know and do not believe that this invention was ever known or used in the United States before my or our invention thereof or patented or described in any printed publication in any country before my or our invention thereof or more than one year prior to this application or said international application, or in public use or on sale in the United States of America more than one year prior to this application or said international application, or that the invention has been patented or made the subject of an inventor's certificate issued before the date of this application or said international application in any country foreign to the United States of America on an application filed by me or my legal representatives or assigns more than twelve months prior to this application or said international application, or that any application for patent or inventor's certificate on this invention has been filed in any country foreign to the United States of America prior to this application or said international application by me or my legal representatives or assigns except as identified below.

COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION
(Page 2)

Attorney Docket No. 1098-02

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT International Application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application(s) for patent or inventor's certificate, or of any PCT International Application having a filing date before that of the application on which priority is claimed:

Number	Country	Date of Filing (day,month,year)	Priority Claimed
290345/99	Japan	12 October, 1999	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no
358851/99	Japan	17 December, 1999	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no
358849/99	Japan	17 December, 1999	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no
39192/2000	Japan	17 February, 2000	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no
			<input type="checkbox"/> yes <input type="checkbox"/> no

I hereby claim the benefit under Title 35, United States Code, §119(e) or §120 (as applicable) of any United States application(s), or §365(c) of any PCT International Application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International Application(s) in the manner provided by the first paragraph of Title 35, United States Code, §112:

(Application Serial No.)

(Filing Date)

(Status)(patented,pending,abandoned)

(Application Serial No.)

(Filing Date)

(Status)(patented,pending,abandoned)

POWER OF ATTORNEY: As a named inventor, I hereby appoint the registered attorneys listed under Customer No. 022469 and the following registered attorneys to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith:

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COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION
(Page 3)

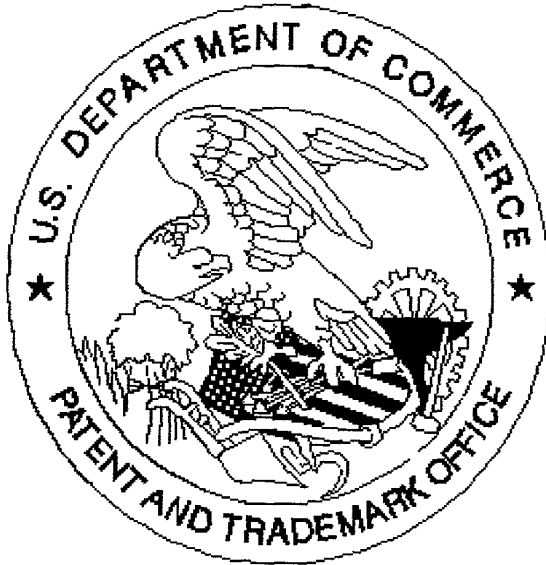
Attorney Docket No. 1098-02

I hereby petition for grant of a United States Letters Patent on this invention.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1. FULL NAME OF SOLE OR FIRST INVENTOR <u>Hideo Matsuoka</u>		INVENTOR'S SIGNATURE <u>Hideo Matsuoka</u>	DATE March 1, 2002
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POST OFFICE ADDRESS			
5. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
6. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
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